# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5871118

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
TAKUYA NARUTOMI	11/30/2019
JUN WATANABE	12/02/2019
SHIGERU SUZUKI	12/05/2019

## **RECEIVING PARTY DATA**

Name:	DENKA COMPANY LIMITED	
Street Address:	1-1, NIHONBASHI-MUROMACHI 2-CHOME, CHUO-KU,	
City:	TOKYO	
State/Country:	JAPAN	
Postal Code:	1038338	

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16621567

## **CORRESPONDENCE DATA**

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: docketing@steinip.com

Correspondent Name: STEIN IP, LLC

Address Line 1: 1990 M STREET, NW

Address Line 2: SUITE 610

Address Line 4: WASHINGTON, D.C. 20036

ATTORNEY DOCKET NUMBER:	0271.1024	
NAME OF SUBMITTER:	MICHAEL D. STEIN	
SIGNATURE:	/Michael D. Stein/	
DATE SIGNED:	12/17/2019	

**Total Attachments: 1** 

source=DeclarationAssignment#page1.tif

PATENT REEL: 051302 FRAME: 0341

505824288

Form (Rev. 4/2013)

#### **UNITED STATES**

Docket No.: 0271,1024

## COMBINED DECLARATION/ASSIGNMENT FOR UTILITY/DESIGN PATENT APPLICATION

#### **OATH OR DECLARATION**

As a below named inventor, I hereby declare that:

This combined declaration and assignment is directed to the application entitled:

POSITIVE ELECTRODE COMPOSITION
the specification of which is attached hereto, or was filed on June 13, 2018 as United States Application Number (or PCT International
Application Number) PCT/JP2018/022554 and was amended on (if applicable).
Any registered attorney of STEIN IP, LLC, 1990 M St., N.W., Suite 610, Washington, D.C. 20036 (202-216-9505), USPTO Customer Number 49,455, is hereby authorized to insert the specified data into the above paragraph, when known.
The above-identified application was made or authorized to be made by me.
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.
<u>ASSIGNMENT</u>
IN CONSIDERATION of good and valuable consideration paid to me, an undersigned inventor, by
DENKA COMPANY LIMITED 1-1, Nihonbashi-Muromachi 2-chome, Chuo-ku, Tokyo 1038338 Japan
(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, I hereby sell, assign and transfer to ASSIGNEE the entire and exclusive right, title and interest to the above-identified application and the claimed invention therein, and any continuation, division, renewal, substitute, reissue or reexamination application based thereon (collectively, hereinafter, "said application(s)"), and all Letters Patent of the United States granted on said application(s), for the full term or terms for which the said Letters Patent may be granted and including any extensions thereof (collectively, hereinafter, "said Letters Patent").
I agree, when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent, in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.
I covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.
IN WITNESS WHEREOF, I have affixed my signature on the date beneath.
Full name of sole/first inventor _Takuya NARUTOMI
Inventor's Signature Tokuya Novutemi Date Executed Nov. 30, 2019
Inventor's Mailing Address <u>c/o Denka Company Limited, Denka Innovation Center, 5-1, Asahi-machi 3-chome, Machida-city, Tokyo</u> 1948560 Japan
Inventor's Residence <u>c/o Denka Company Limited, Denka Innovation Center, 5-1, Asahi-machi 3-chome, Machida-city, Tokyo</u> 1948560 Japan
Full name of second inventor Jun WATANABE
Inventor's Signature
1948560 Japan
Inventor's Residence <u>c/o Denka Company Limited, Denka Innovation Center, 5-1, Asahi-machi 3-chome, Machida-city, Tokyo</u> 1948560 Japan
Full name of third inventor Shigeru SUZUKI
Inventor's Signature Shigern Supply Date Executed Dec. 5 2019
Inventor's Mailing Address <u>c/o Denka Company Limited, Denka Innovation Center, 5-1, Asahi-machi 3-chome, Machida-city, Tokyo 1948560 Japan</u>
Inventor's Residence c/o Denka Company Limited, Denka Innovation Center, 5-1, Asahi-machi 3-chome, Machida-city, Tokyo

 $\begin{array}{c} \text{PATENT}_{\text{[Page 1 of 1]}} \\ \text{REEL: 051302 FRAME: 0342} \end{array}$ 

**RECORDED: 12/17/2019** 

1948560 Japan